

AAA3528RBGS/08-09

3.2 x 2.8 mm Surface Mount LED Lamp



DESCRIPTIONS

- The Hyper Red source color devices are made with AIGaInP on GaAs substrate Light Emitting Diode
- The Blue source color devices are made with InGaN Light Emitting Diode
- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode
- · Electrostatic discharge and power surge could damage the LEDs
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- · All devices, equipments and machineries must be electrically grounded

FEATURES

- · Suitable for all SMD assembly and solder process
- · Available on tape and reel
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- Halogen-free
- RoHS compliant

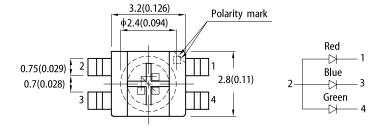
APPLICATIONS

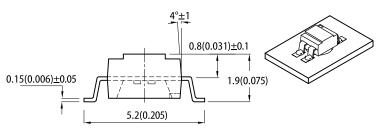
- Backlight
- Status indicator
- · Home and smart appliances
- · Wearable and portable devices
- · Healthcare applications

ATTENTION

Observe precautions for handling electrostatic discharge sensitive devices



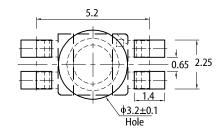




RECOMMENDED SOLDERING PATTERN

PACKAGE DIMENSIONS

(units : mm; tolerance : ± 0.1)



Notes

- All dimensions are in millimeters (inches).
 Tolerance is ±0.2(0.008") unless otherwise noted.
 The specifications, characteristics and technical data described in the datasheet are subject to
- change without prior notice. The device has a single mounting surface. The device must be mounted according to the specifications.

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	lv (mcd) @ 20mA ^[2]		Viewing Angle ^[1]
			Min.	Тур.	201/2
AAA3528RBGS/08-09	Hyper Red (AlGaInP)	Water Clear	55	110	
	Blue (InGaN)		55	100	120°
	Green (InGaN)		400	500	

Notes

41/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 Luminous intensity / luminous flux: +/-15%.
 Luminous intensity value is traceable to CIE127-2007 standards.

ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Davana dav			Va	Value	
Parameter	Symbol	Emitting Color	Тур.	yp. Max.	
Wavelength at Peak Emission I_F = 20mA	λ _{peak}	Hyper Red Blue Green	645 460 515	-	nm
Dominant Wavelength I_F = 20mA	λ_{dom} ^[1]	Hyper Red Blue Green	630 465 525	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 20mA	Δλ	Hyper Red Blue Green	28 25 35	-	nm
Capacitance	с	Hyper Red Blue Green	35 100 45	-	pF
Forward Voltage I _F = 20mA	V _F ^[2]	Hyper Red Blue Green	1.95 3.3 3.3	2.5 4 4.1	V
Reverse Current (V _R = 5V)	I _R	Hyper Red Blue Green	-	10 50 50	μA
Temperature Coefficient of λ_{peak} I_F = 20mA, -10°C $\leq T \leq 85^\circ C$	TC _{λpeak}	Hyper Red Blue Green	0.14 0.04 0.05	-	nm/°C
Temperature Coefficient of λ_{dom} I_F = 20mA, -10°C \leq T \leq 85°C	TC _{λdom}	Hyper Red Blue Green	0.05 0.03 0.03	-	nm/°C
Temperature Coefficient of V_F I _F = 20mA, -10°C \leq T \leq 85°C	TCv	Hyper Red Blue Green	-1.9 -2.9 -2.9	-	mV/°C

Notes:

1. The dominant wavelength (λ d) above is the setup value of the sorting machine. (Tolerance λ d: ±1nm.)

Forward voltage: 10.10V.
 Wavelength value is traceable to CIE127-2007 standards.
 Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

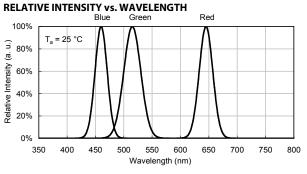
ABSOLUTE MAXIMUM RATINGS at T₄=25°C

	Symbol	Value			
Parameter		Hyper Red	Blue	Green	Unit
Power Dissipation	PD	75	120	123	mW
Reverse Voltage	V _R	5	5	5	V
Junction Temperature	Tj	115	115	115	°C
Operating Temperature	T _{op}	-40 to +85			°C
Storage Temperature	T _{stg}	-40 to +85			°C
DC Forward Current	I _F	30	30	30	mA
Peak Forward Current	۱ _{FM} ^[1]	185	150	150	mA
Electrostatic Discharge Threshold (HBM)	-	3000	250	450	V
Thermal Resistance (Junction / Ambient)	R _{th JA} ^[2]	360	430	420	°C/W
Thermal Resistance (Junction / Solder point)	R _{th JS} ^[2]	200	270	250	°C/W

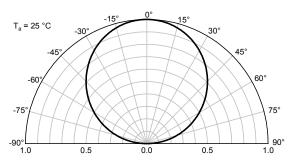
Notes: 1. 1/10 Duty Cycle, 0.1ms Pulse Width. 2. R_{th JA}, R_{th JS} Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad). 3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

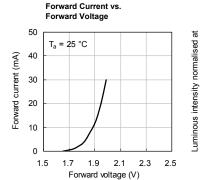
AAA3528RBGS/08-09

TECHNICAL DATA

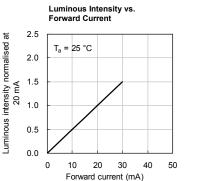


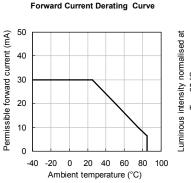
SPATIAL DISTRIBUTION



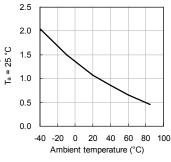


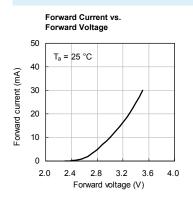
HYPER RED



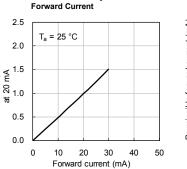




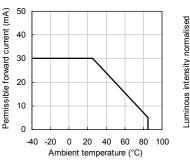




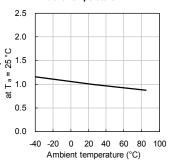
Luminous Intensity vs.



Forward Current Derating Curve



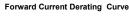
Luminous Intensity vs. Ambient Temperature



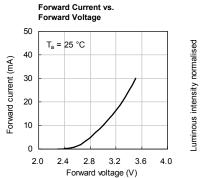
GREEN

Permissible forward current (mA)

BLUE



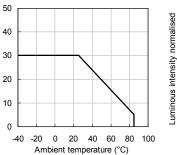
Luminous Intensity vs.



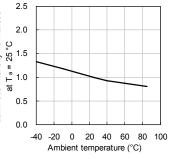
Forward Current 2.5 2.0 T_a = 25 °C 1.5 0.5 0.5

Forward current (mA)

Luminous Intensity vs.



Ambient Temperature



Picon Spec No: DSAP5521 / 1201008391 Rev No: V.5B Date: 01/04/2021

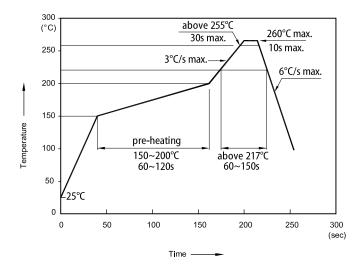
0.0

0 10 20 30 40 50

Luminous intensity normalised

AAA3528RBGS/08-09

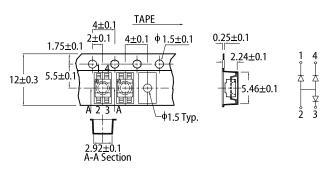
REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS



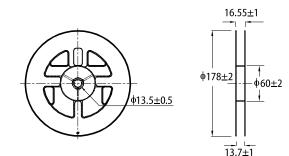
Notes.

 Don't cause stress to the LEDs while it is exposed to high temperature.
 The maximum number of reflow soldering passes is 2 times.
 Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product

TAPE SPECIFICATIONS (units : mm)



REEL DIMENSION (units : mm)



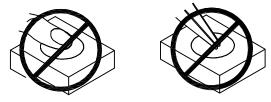
HANDLING PRECAUTIONS

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.



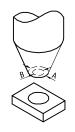
2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



- 4-1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4-2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4-3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.
- 5. As silicone encapsulation is permeable to gases, some corrosive substances such as H₂S might corrode silver plating of lead frame. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

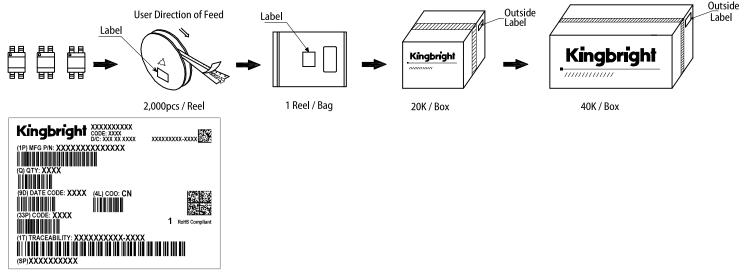
3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.





AAA3528RBGS/08-09

PACKING & LABEL SPECIFICATIONS



PRECAUTIONARY NOTES

- The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to 2. the latest datasheet for the updated specifications. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If
- 3.
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